

What is claimed is:

1. An apparatus for manufacturing semiconductor device comprising:

5 an enclosing structure defining a closed space isolated from an external environment;

a purifying system for keeping atmosphere in the closed space clean;

a processing device disposed in said closed space  
10 for processing a semiconductor wafer; and

a pressure elevating device for keeping an internal pressure high in said closed space so as to be higher than a pressure in said external environment.

15 2. An apparatus according to claim 1, wherein said enclosing structure comprises a housing.

3. An apparatus according to claim 1, wherein said purifying system comprises a filter unit mounted on  
20 said enclosing structure for supplying clean air into said closed space.

4. An apparatus according to claim 3, wherein said pressure elevating device comprises a fan disposed in  
25 said filter unit and a damper for adjusting a rate of air discharged from said closed space.

5. An apparatus according to claim 1, wherein said apparatus comprises a polishing apparatus for polishing a semiconductor wafer.

5           6. An apparatus according to claim 5, said polishing apparatus comprising:

          a polishing section for polishing a semiconductor wafer; and

          a cleaning section for cleaning a polished  
10 semiconductor wafer;

          wherein an internal pressure in said cleaning section is higher than an internal pressure in said polishing section.

15           7. An apparatus according to claim 6, further comprising a loading/unloading section for receipt of a semiconductor wafer to be polished and a polished semiconductor wafer;

          wherein an internal pressure in said  
20 loading/unloading section is higher than said internal pressure in said cleaning section.

          8. An apparatus according to claim 6, further comprising a partition having an opening for partitioning  
25 said cleaning section from said polishing section.